

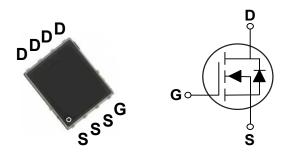
100V N-Channel MOSFETs

Pb RoHS

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5X6 Pin Configuration



Absolute Maximum Ratings Tc=25°C unless otherwise noted

BV _{DSS}	R _{DS(ON)}	I _D
100 V	4.4 mΩ	142 A

Features

- $R_{DS(ON)} \leq 4.4 m\Omega @V_{GS} = 10V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available

Applications

- Power Management in DC/DC Converters
- USB Power Delivery (USB PD)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I	Drain Current – Continuous (T _C =25°C)	142	Α
Ι _D	Drain Current – Continuous (T _C =100°C)	107	А
I _{DM}	Drain Current – Pulsed (NOTE 1)	400	А
EAS	Single Pulse Avalanche Energy (L=0.1mH) (NOTE 2)	162	mJ
IAS	Single Pulse Avalanche Current (L=0.1mH) (NOTE 2)	57	А
P _D	Power Dissipation (T _C =25°C)	125	W
TJ	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
Marking Code		NM4P4	

Thermal Characteristics

Symbol	Parameter Rating		Unit
R _{θJA}	Thermal Resistance Junction to Ambient	48	°C/W
R _{eJC}	Thermal Resistance Junction to Case	1	°C/W





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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			4.4	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2.0	3.0	4.0	V
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		22		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Qg	Total Gate Charge			72.8		
Q_gs	Gate-Source Charge	V_{DS} =50V , V_{GS} =10V , I_{D} =20A		21.5		nC
Q_gd	Gate-Drain Charge	1 Г		20.7		
$T_{d(on)}$	Turn-On Delay Time			12.8		
T _r	Rise Time	V_{DS} =25V , V_{GS} =10V , R_{GEN} =3 Ω , I_{D} =1A		6.3		nS
$T_{d(off)}$	Turn-Off Delay Time			40		113
T _f	Fall Time			65		
C _{iss}	Input Capacitance			4175		
C _{oss}	Output Capacitance	V _{DS} =50V , V _{GS} =0V , F=1MHz		1190		pF
C _{rss}	Reverse Transfer Capacitance			35		
R _g	Gate Resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		0.6		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =10A			1.1	V
t _{rr}	Reverse Recovery Time	V _R =50V , I _F =10A ,		40.4		nS
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/us		80.2		nC

NOTES :

1. Max. current is limited by bonding wire.

2. UIS tested and pulse width are limited by maximum junction temperature 150° C.

3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

4. Guaranteed by design, not subject to production testing.





Characteristics Curves

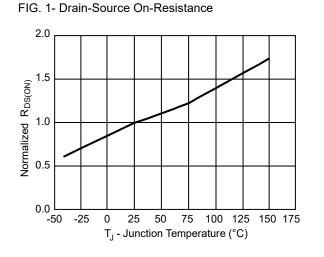


FIG. 3- Gate Charge Characteristics

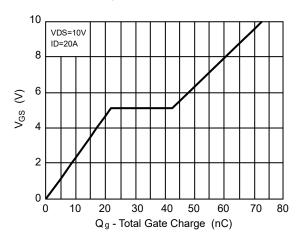


FIG. 5- Safe Operating Area

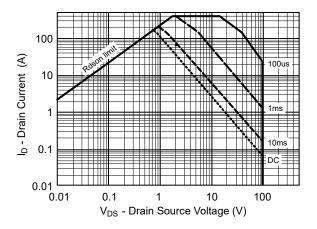


FIG. 2- Gate Threshold Voltage

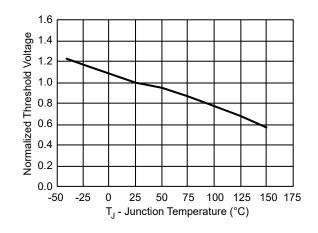


FIG. 4- Drain Current

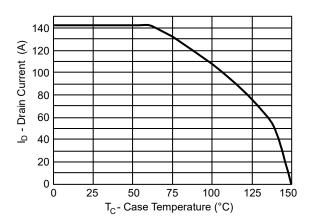
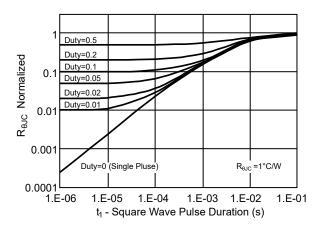


FIG. 6- $R_{\theta JC}$ Transient Thermal Impedance

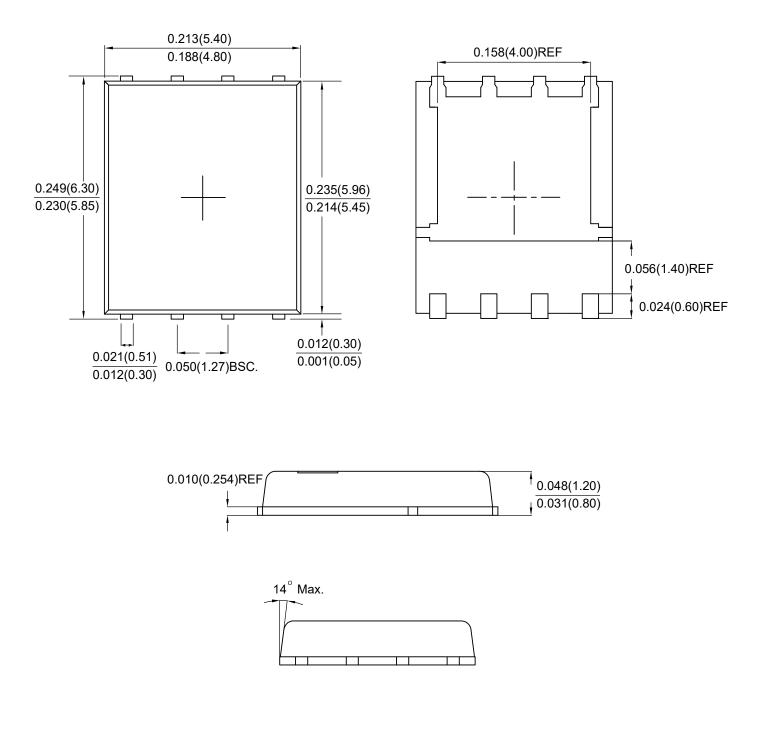




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Package Outline Dimensions



PPAK5X6 Dimensions in inches and (millimeters)



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